

# 46-7450 Economy Version

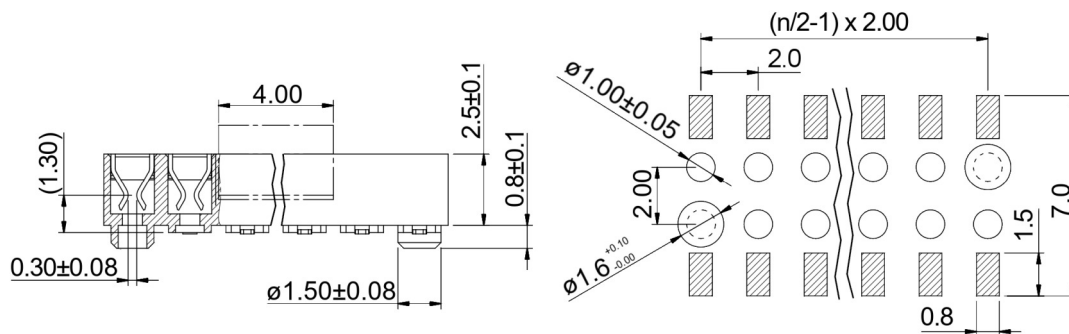
SMT-Buchsenleisten RM 2,00mm, stehend, 2-reihig – durchsteckbar  
SMT Female Headers, 2.00mm Pitch, Vertical, Double Row – Pass Through

## Technische Daten / Technical Data

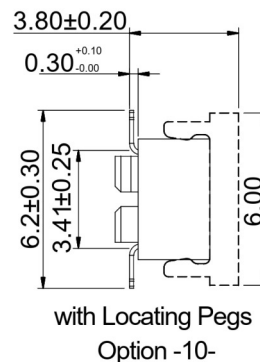
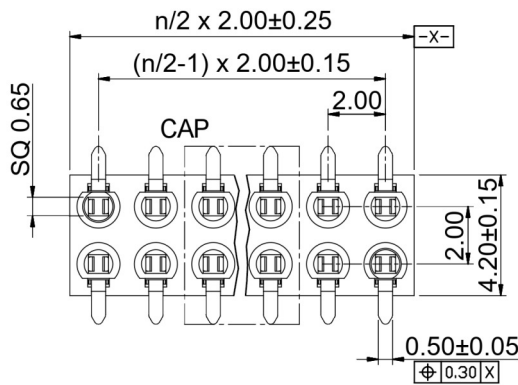
Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ < 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ > 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	500 V AC/DC 500 V AC/DC
Nennstrom <i>Current Rating</i>	2 A 2 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +125 °C -40 °C ... +125 °C
Verarbeitung <i>Processing</i>	230 °C für 30-60 Sekunden (260 °C für 5 Sek., Type 11) (260 °C für 10 Sek., Type 30) 230 °C for 30-60 seconds (260 °C for 5 sec., Type 11) (260 °C for 10 sec., Type 30)



Doppelfederkontakte für Vierkantstifte 0,50mm.  
Dual beam contacts accept 0.50mm square pins.



Recommended PCB Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)

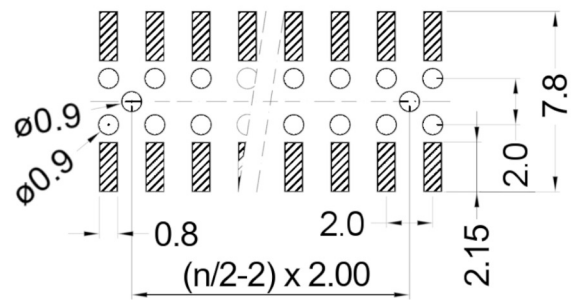
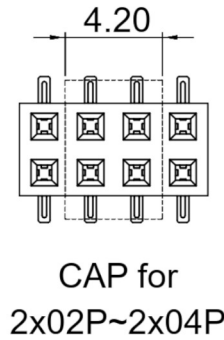
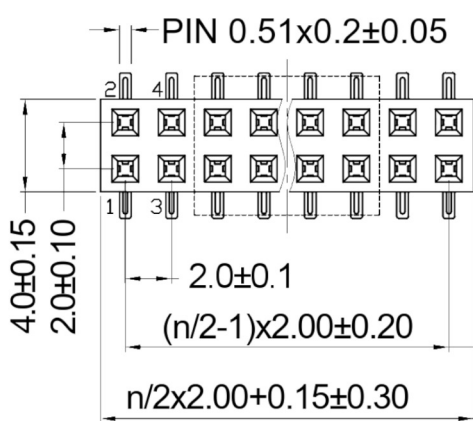


<b>Series</b>	<b>Contacts*</b>	<b>Type</b>	<b>Plating</b>	<b>Locating Pegs</b>	<b>Packaging*</b>
<b>46-7450</b>	<b>20</b> 04-44 Type 11	<b>11</b> 11 H=2,8mm, Eingang unten H=2.8mm, bottom entry	<b>00</b> Vergoldet Gold plated	<b>10</b> Mit Pos.hilfen With loc. pegs	<b>PPTR</b> ST PPST PPTR

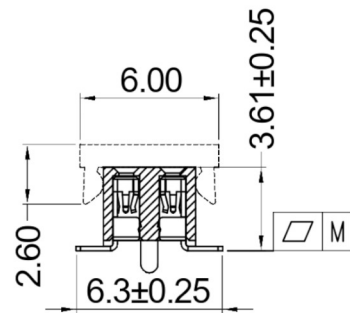
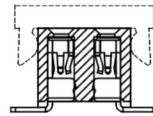
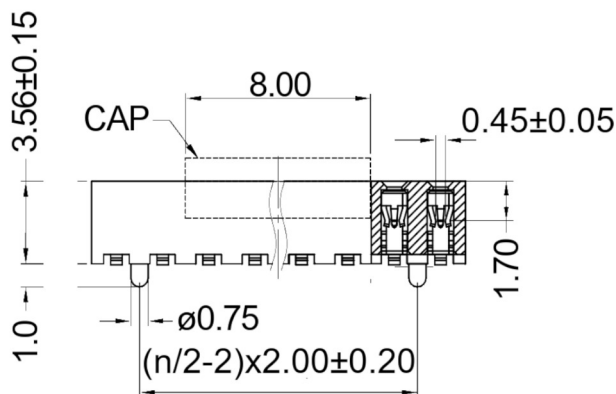
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Recommended PCB Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)



Series	Contacts*	Type	Plating	Locating Pegs*	Packaging*
<b>46-7450</b>	<b>20</b> 04-50 Type 30	<b>30</b> 30 H=3,6mm, Eingang oben H=3.6mm, top entry	<b>00</b> 00 Vergoldet Gold plated	<b>10</b> 00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen With loc. pegs	<b>PPTR</b> ST In Stangen ohne Pick&Place-Pads In tubes w/o Pick&Place-Pads PPST In Stangen mit Pick&Place-Pads In tubes with Pick&Place-Pads PPTR Tape & Reel mit Pick&Place-Pads Tape & Reel with Pick&Place-Pads

\* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.  
\* This is an **order example** - please replace by your specifications.

### Lieferformen / Packaging Options:

ST In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads  
PPST In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads  
PPTR Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&Place-Pads

### Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_{Smin}$	150 °C
Temperatur Maximum $T_{Smax}$	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich $T_L$	untere Temperaturangabe [°C]
Verweildauer oberhalb $T_L$	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur $T_P$	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur $T_P$	max. 8m

### Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_{Smin}$	150 °C
Maximum Temperatur $T_{Smax}$	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature $T_L$	Lower Temperature [°C]
Duration above $T_L$	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature $T_P$	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. $T_P$	max. 8min

